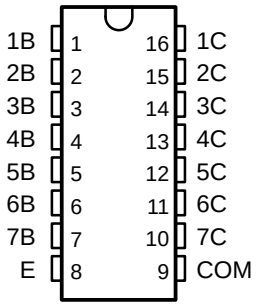
- **Qualification in Accordance With AEC-Q100†**
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **ESD Protection Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **500-mA Rated Collector Current (Single Output)**
- **High-Voltage Outputs . . . 50 V**
- **Output Clamp Diodes**
- **Inputs Compatible With Various Types of Logic**
- **Relay-Driver Applications**

† Contact factory for details. Q100 qualification data available on request.

D PACKAGE
(TOP VIEW)



description

The ULQ2003A-Q1 and ULQ2004A-Q1 are high-voltage, high-current Darlington transistor arrays. Each consists of seven npn Darlington pairs that feature high-voltage outputs with common-cathode clamp diodes for switching inductive loads. The collector-current rating of a single Darlington pair is 500 mA. The Darlington pairs can be paralleled for higher current capability. Applications include relay drivers, hammer drivers, lamp drivers, display drivers (LED and gas discharge), line drivers, and logic buffers.

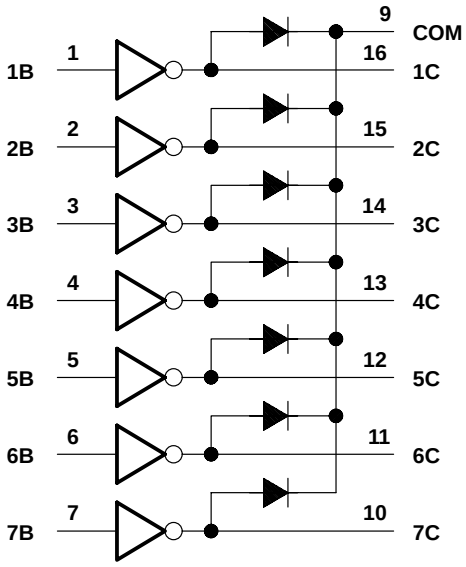
The ULQ2003A-Q1 has a 2.7-kΩ series base resistor for each Darlington pair, for operation directly with TTL or 5-V CMOS devices. The ULQ2004A-Q1 has a 10.5-kΩ series base resistor to allow operation directly from CMOS devices that use supply voltages of 6 V to 15 V. The required input current of the ULQ2004A-Q1 is below that of the ULQ2003A-Q1.

AVAILABLE OPTIONS

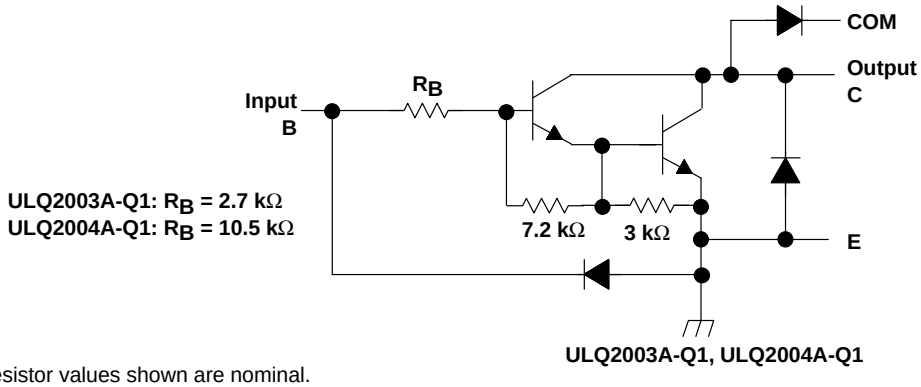
T_A	D PACKAGES†
	SMALL OUTLINE
–40°C to 105°C	ULQ2003ATDQ1 ULQ2003ATDRQ1
	ULQ2004ATDQ1‡ ULQ2004ATDRQ1‡

† The D package is available taped and reeled. Add the suffix R to device type (e.g., ULQ2003TDADRQ1).
‡ ULQ2004ATDQ1 and ULQ2004ATDRQ1 are Product Preview only.

logic diagram



schematics (each Darlington pair)



All resistor values shown are nominal.

absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)†

Collector-emitter voltage	50 V
Clamp diode reverse voltage (see Note 1)	50 V
Input voltage, V_I (see Note 1)	30 V
Peak collector current (see Figure 14)	500 mA
Output clamp current, I_{OK}	500 mA
Total emitter-terminal current	–2.5 A
Continuous total power dissipation	See Dissipation Rating Table
Package thermal impedance, θ_{JA} (see Note 2)	73°C/W
Operating free-air temperature range, T_A,	–40°C to 105°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to the emitter/substrate terminal E, unless otherwise noted.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

DISSIPATION RATING TABLE

PACKAGE	T_A = 25°C POWER RATING	DERATING FACTOR ABOVE T_A = 25°C	T_A = 85°C POWER RATING	T_A = 105°C POWER RATING
D	950 mW	7.6 mW/°C	494 mW	342 mW

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		ULQ2003A-Q1			ULQ2004A-Q1			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
$V_{I(on)}$	On-state input voltage, See Figure 6	V_{CE} = 2 V	I_C = 125 mA						5	V
			I_C = 200 mA			2.7			6	
			I_C = 250 mA			2.9				
			I_C = 275 mA						7	
			I_C = 300 mA			3				
			I_C = 350 mA						8	
$V_{CE(sat)}$	Collector-emitter saturation voltage, See Figure 5	I_I = 250 µA,	I_C = 100 mA		0.9	1.2		0.9	1.1	V
		I_I = 350 µA,	I_C = 200 mA		1	1.4		1	1.3	
		I_I = 500 µA,	I_C = 350 mA		1.2	1.7		1.2	1.6	
I_{CEX}	Collector cutoff current	V_{CE} = 50 V, I_I = 0, See Figure 1				100			50	µA
		V_{CE} = 50 V, See Figure 2	I_I = 0						100	
			V_I = 1 V						500	
V_F	Clamp forward voltage, See Figure 8	I_F = 350 mA			1.7	2.2		1.7	2	V
$I_{I(off)}$	Off-state input current, See Figure 3	V_{CE} = 50 V,	I_C = 500 µA	30	65		50	65		µA
I_I	Input current, see Figure 4	V_I = 3.85 V			0.93	1.35				mA
		V_I = 5 V						0.35	0.5	
		V_I = 12 V						1	1.45	
I_R	Clamp reverse current, See Figure 7	V_R = 50 V,	T_A = 25°C			100			50	µA
		V_R = 50 V				100			100	
C_i	Input capacitance	V_I = 0,	f = 1 MHz		15	25		15	25	pF

switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	ULQ2003A-Q1, ULQ2004A-Q1			UNIT
			MIN	TYP	MAX	
t_{PLH}	Propagation delay time, low-to-high level output	See Figure 9		1	10	µs
t_{PHL}	Propagation delay time, high-to-low level output	See Figure 9		1	10	µs
V_{OH}	High-level output voltage after switching	V_S = 50 V, $I_O \approx$ 300 mA, See Figure 10	V_S–500			mV

PARAMETER MEASUREMENT INFORMATION

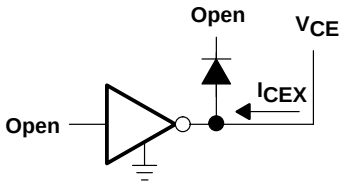


Figure 1. I_{CEX} Test Circuit

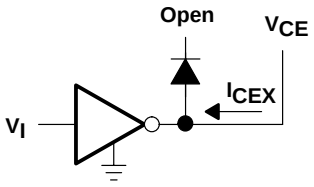


Figure 2. I_{CEX} Test Circuit

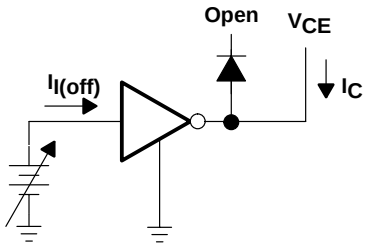


Figure 3. $I_{I(off)}$ Test Circuit

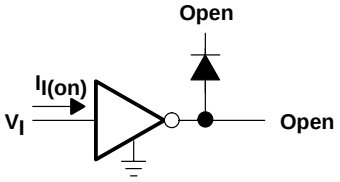
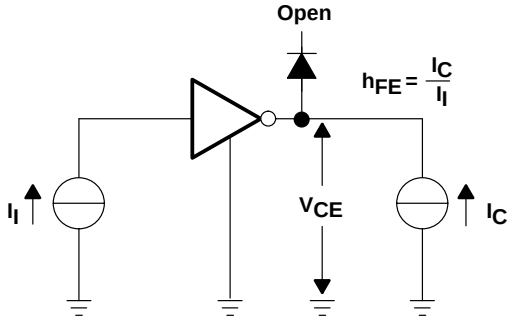


Figure 4. I_I Test Circuit



NOTE: I_I is fixed for measuring $V_{CE(sat)}$, variable for measuring h_{FE}.

Figure 5. h_{FE}, $V_{CE(sat)}$ Test Circuit

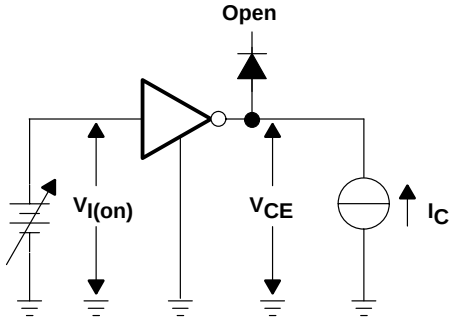


Figure 6. $V_{I(on)}$ Test Circuit

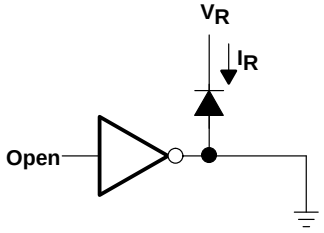


Figure 7. I_R Test Circuit

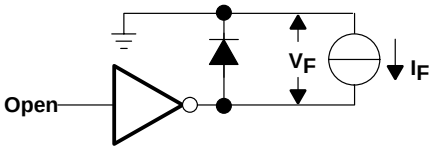
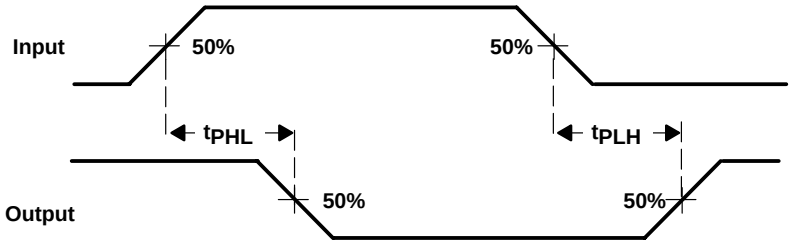


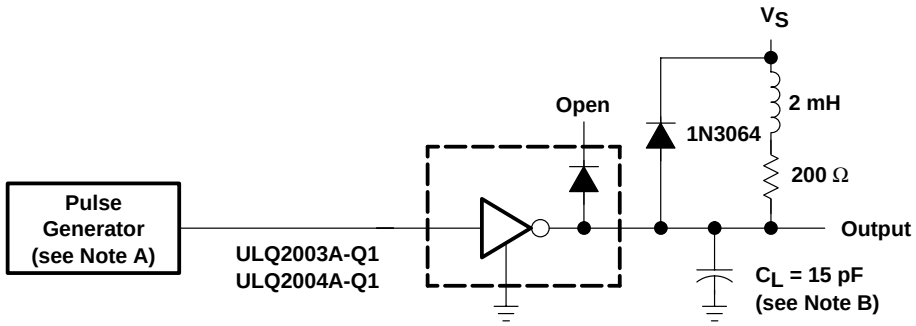
Figure 8. V_F Test Circuit

PARAMETER MEASUREMENT INFORMATION

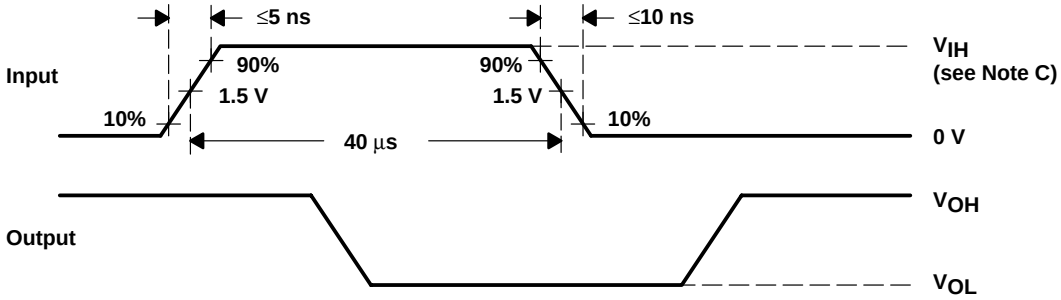


VOLTAGE WAVEFORMS

Figure 9. Propagation Delay-Time Waveforms



TEST CIRCUIT



VOLTAGE WAVEFORMS

Figure 10. Latch-Up Test Circuit and Voltage Waveforms

NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.
C. For testing the ULQ2003A-Q1, V_{IH} = 3 V; for the ULQ2004A-Q1, V_{IH} = 8 V.

TYPICAL CHARACTERISTICS

COLLECTOR-EMITTER SATURATION VOLTAGE
vs
COLLECTOR CURRENT
(ONE DARLINGTON)

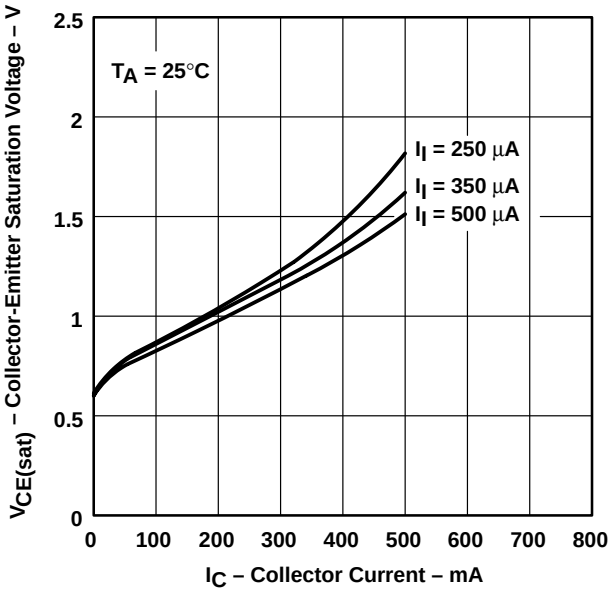


Figure 11

COLLECTOR-EMITTER SATURATION VOLTAGE
vs
TOTAL COLLECTOR CURRENT
(TWO DARLINGTONS IN PARALLEL)

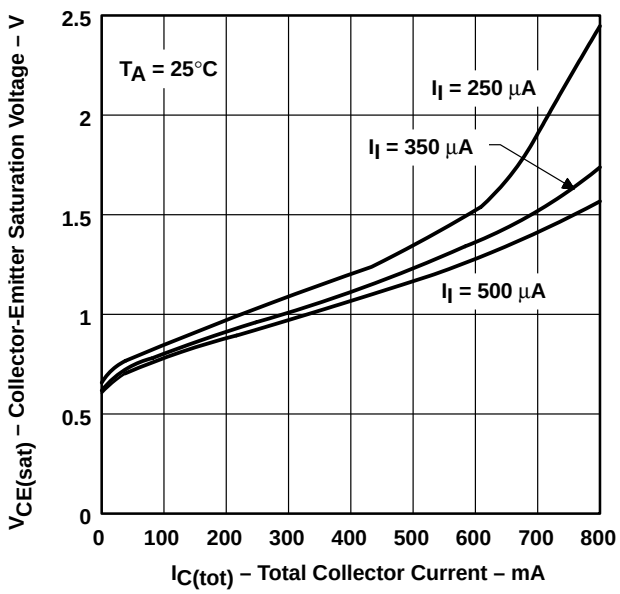


Figure 12

COLLECTOR CURRENT
vs
INPUT CURRENT

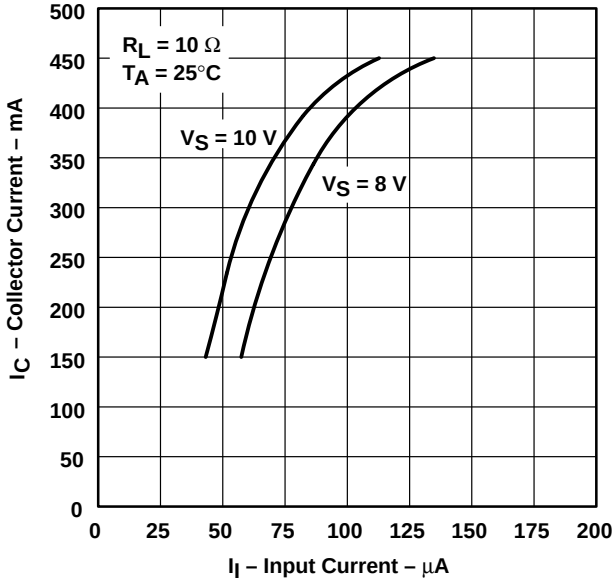


Figure 13

THERMAL INFORMATION

MAXIMUM COLLECTOR CURRENT
vs
DUTY CYCLE

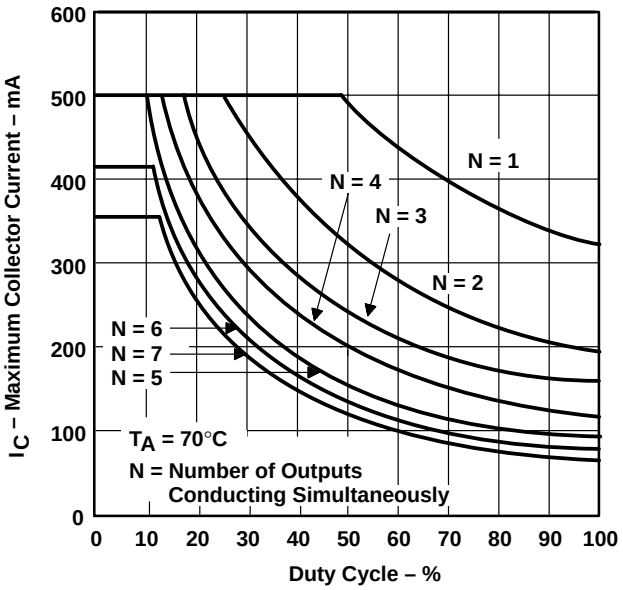


Figure 14

APPLICATION INFORMATION

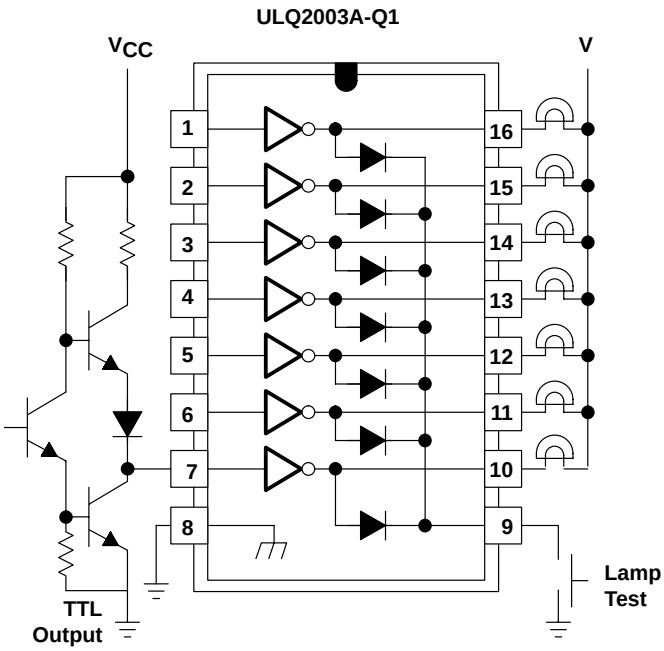


Figure 15. TTL to Load

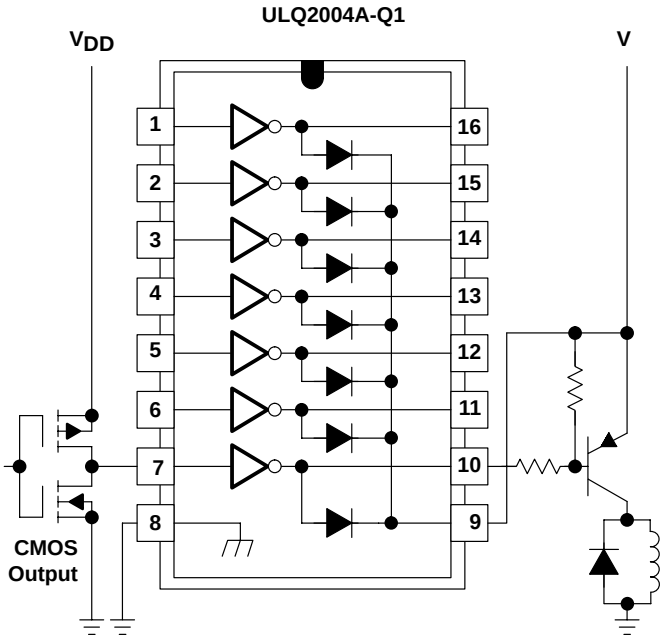


Figure 16. Buffer for Higher Current Loads

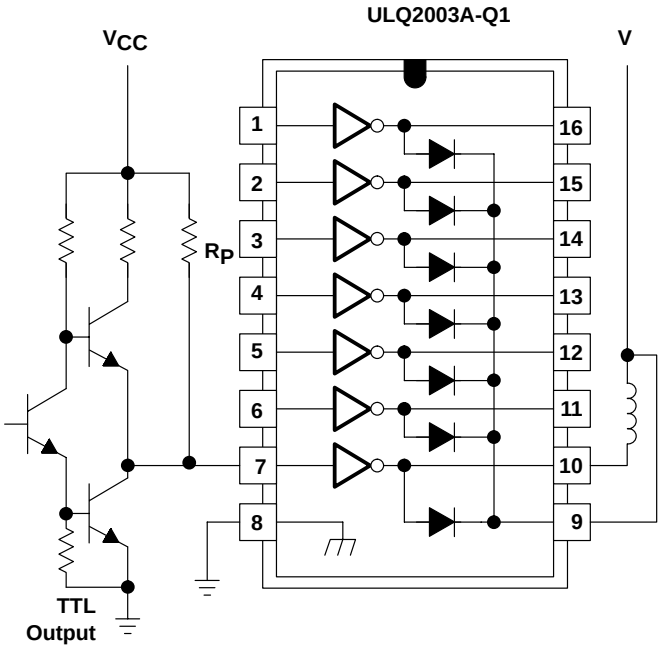
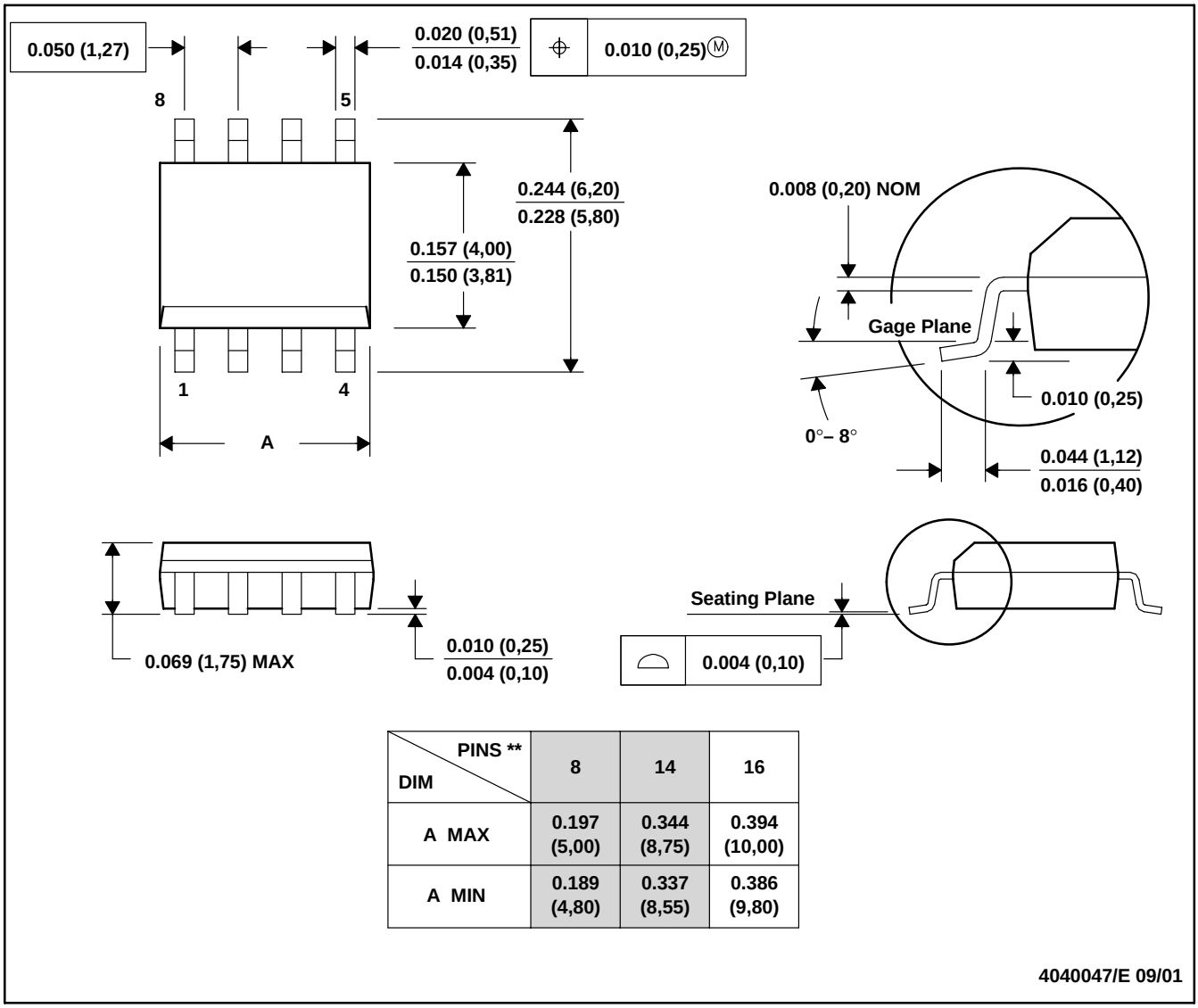


Figure 17. Use of Pullup Resistors to Increase Drive Current

MECHANICAL DATA

D (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

8 PINS SHOWN



DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

4040047/E 09/01

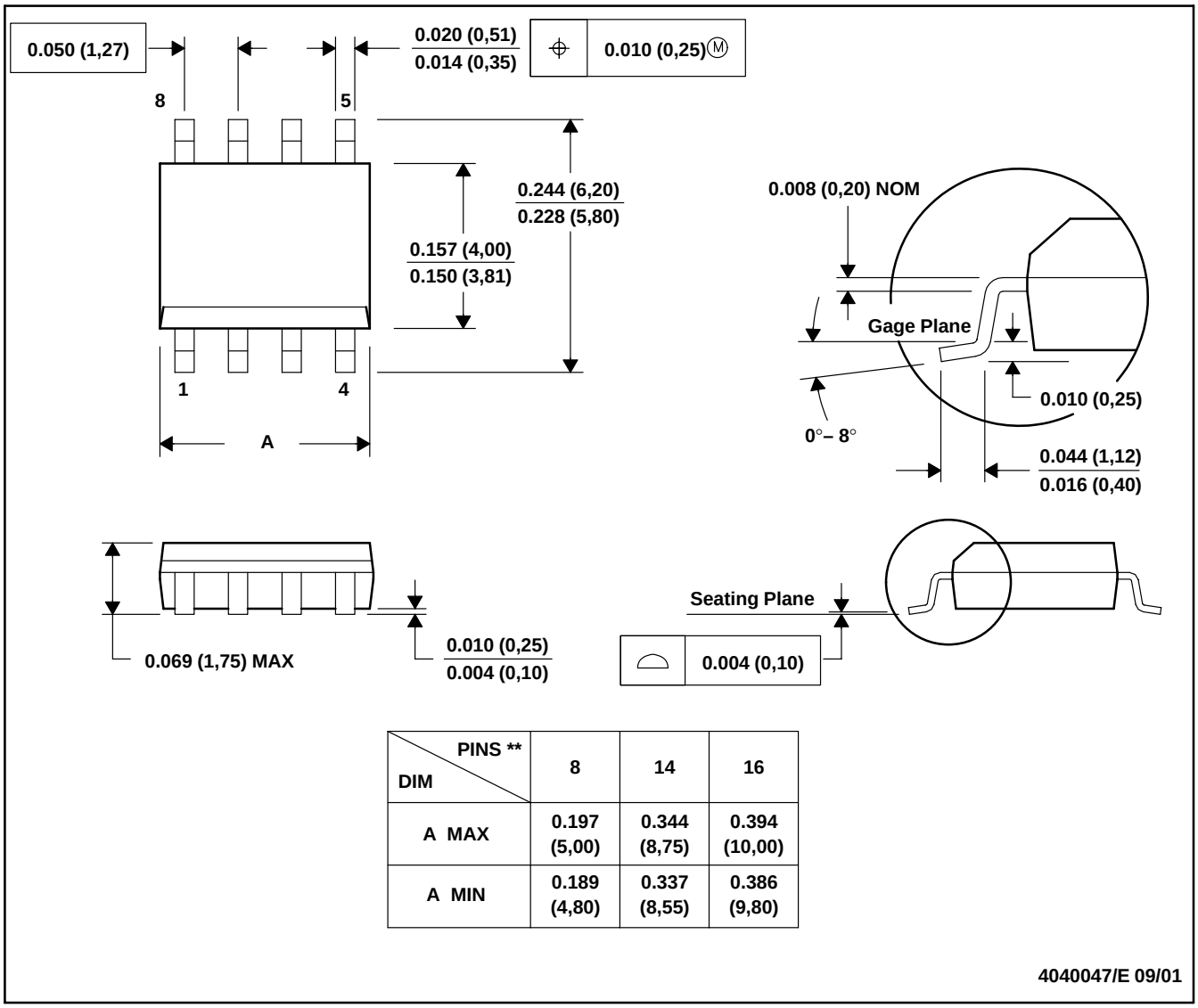
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-012

MSOI002B – JANUARY 1995 – REVISED SEPTEMBER 2001

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



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4040047/E 09/01

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